

## N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
200	0.130 at $V_{GS} = 10$ V	3
	0.142 at $V_{GS} = 6.0$ V	2.8

### FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 %  $R_g$  Tested

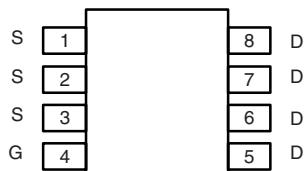


**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available

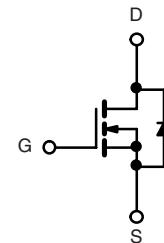
### APPLICATIONS

- Primary Side Switch

SO-8



Top View



N-Channel MOSFET

**Ordering Information:** Si4418DY-T1-E3 (Lead (Pb)-free)  
Si4418DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	200		V
Gate-Source Voltage		$V_{GS}$	$\pm 20$		
Continuous Drain Current ( $T_J = 150$ °C) <sup>a</sup>	$T_A = 25$ °C	$I_D$	3	2.3	A
	$T_A = 85$ °C		2.1	1.6	
Pulsed Drain Current		$I_{DM}$	12		
Avalanche Current	$L = 0.1$ mH	$I_{AS}$	6		
Single Avalanche Energy (Duty Cycle $\leq 1$ %)			$E_{AS}$	1.8	mJ
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	2.1	1.25	A
Maximum Power Dissipation <sup>a</sup>	$T_A = 25$ °C	$P_D$	2.5	1.5	W
	$T_A = 85$ °C		1.3	0.8	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 10$ s	$R_{thJA}$	36	50	°C/W
	Steady State		71	85	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	15	20	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

**SPECIFICATIONS**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2		4	V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 200 \text{ V}$ , $V_{GS} = 0 \text{ V}$		1		$\mu\text{A}$
		$V_{DS} = 200 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 85^\circ\text{C}$		20		
		$V_{DS} \geq 5 \text{ V}$ , $V_{GS} = 10 \text{ V}$	12			
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{GS} = 10 \text{ V}$ , $I_D = 3 \text{ A}$		0.110	0.130	$\Omega$
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = 6.0 \text{ V}$ , $I_D = 2.8 \text{ A}$		0.120	0.142	
		$V_{GS} = 15 \text{ V}$ , $I_D = 3 \text{ A}$		13		S
Forward Transconductance <sup>a</sup>	$g_{fs}$	$I_S = 2.1 \text{ A}$ , $V_{GS} = 0 \text{ V}$		0.8	1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 100 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 3 \text{ A}$		20	30	nC
Gate-Source Charge	$Q_{gs}$			4.5		
Gate-Drain Charge	$Q_{gd}$			6.5		
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$	1	2	3.4	$\Omega$
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 100 \text{ V}$ , $R_L = 100 \Omega$ $I_D \geq 1 \text{ A}$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 6 \Omega$		15	25	ns
Rise Time	$t_r$			15	25	
Turn-Off Delay Time	$t_{d(\text{off})}$			40	60	
Fall Time	$t_f$			20	30	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = 2.1 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$		70	110	

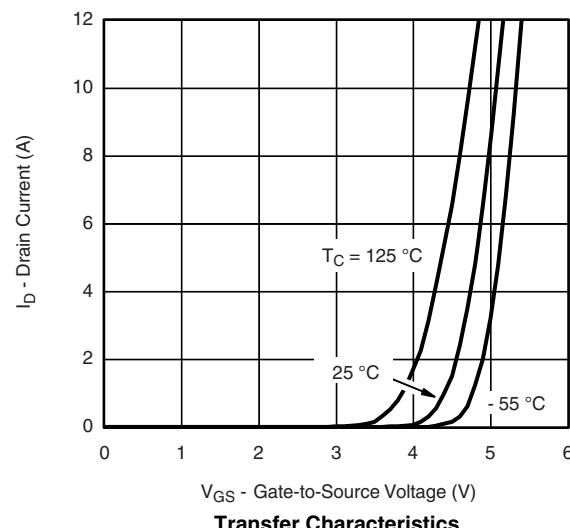
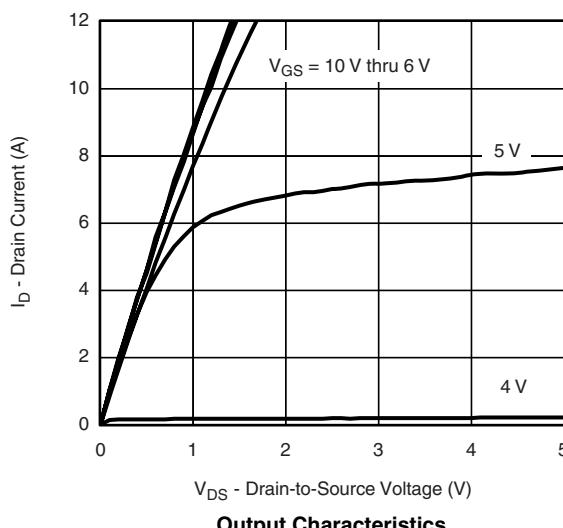
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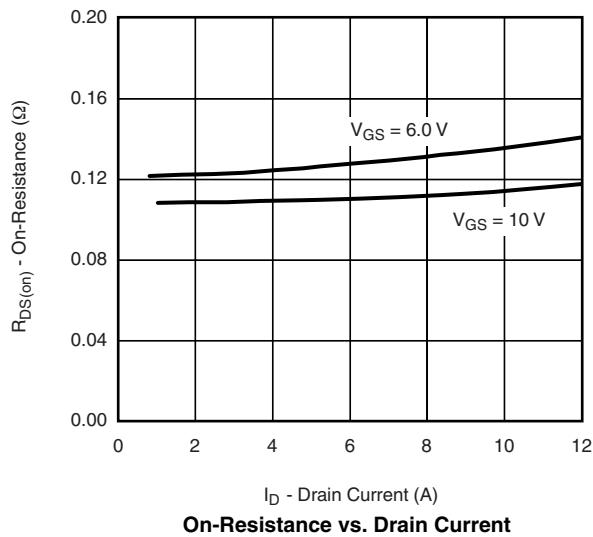
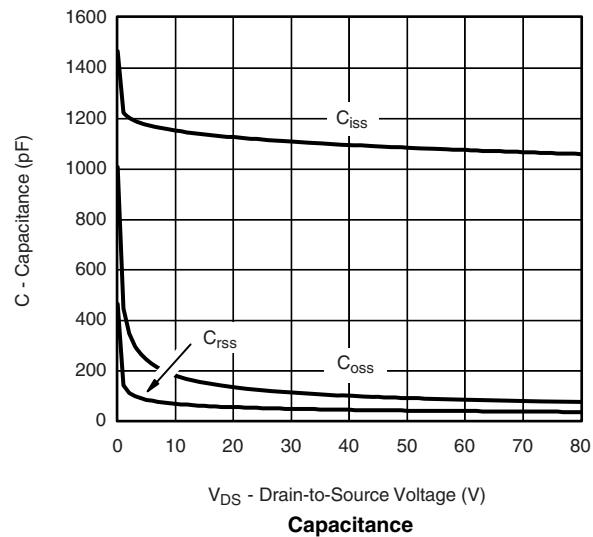
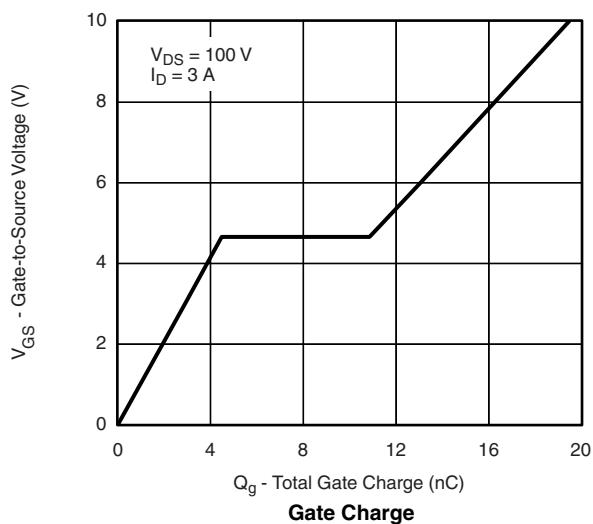
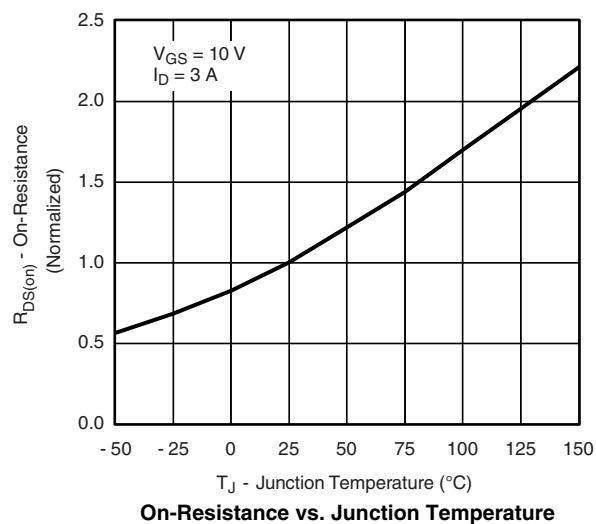
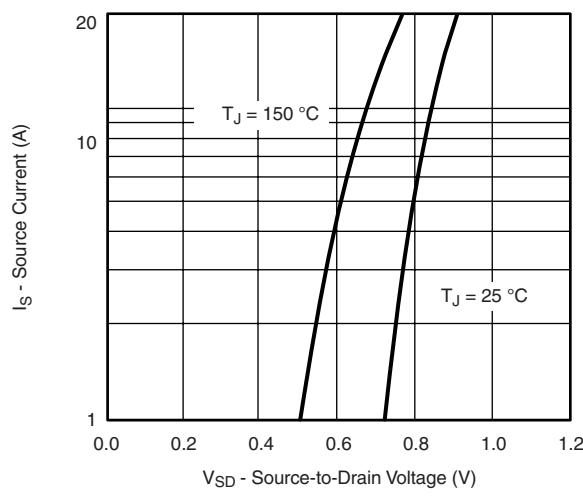
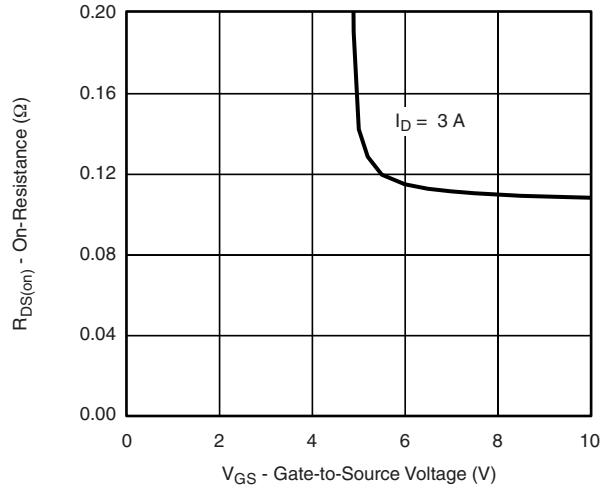
a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .

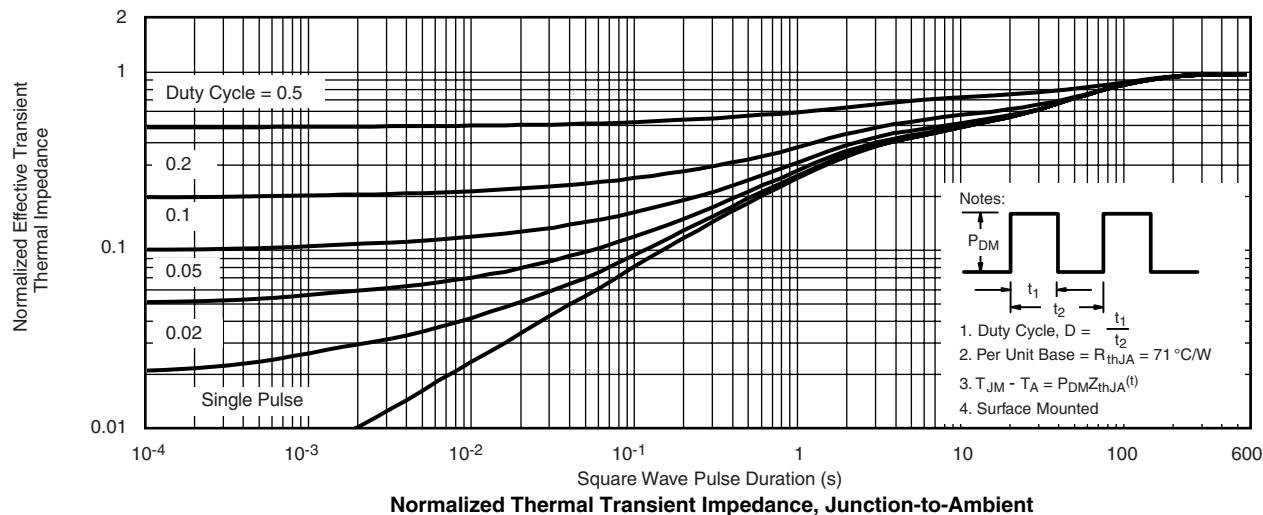
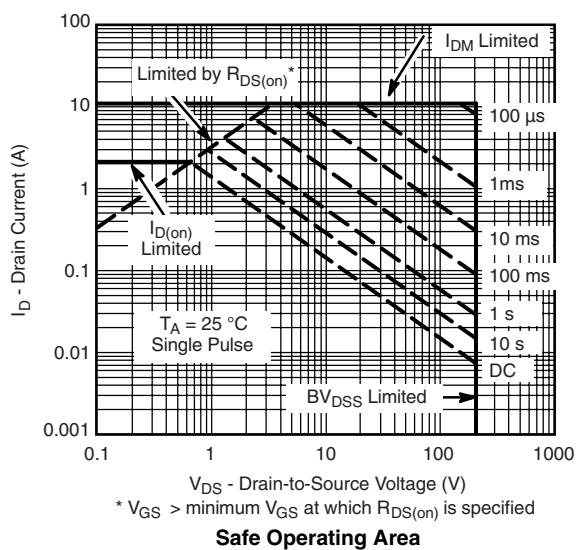
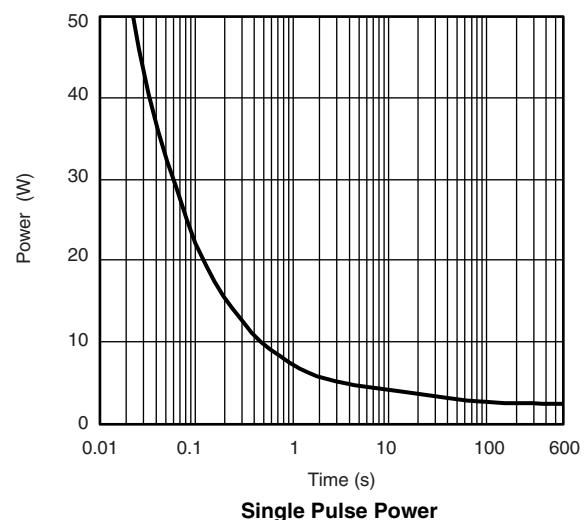
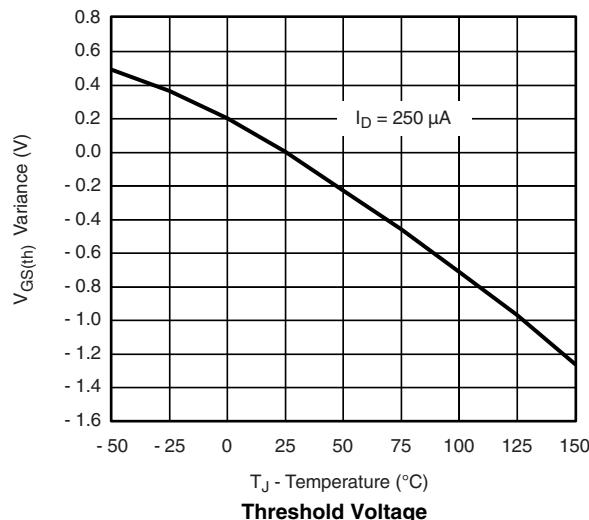
b. Guaranteed by design, not subject to production testing.

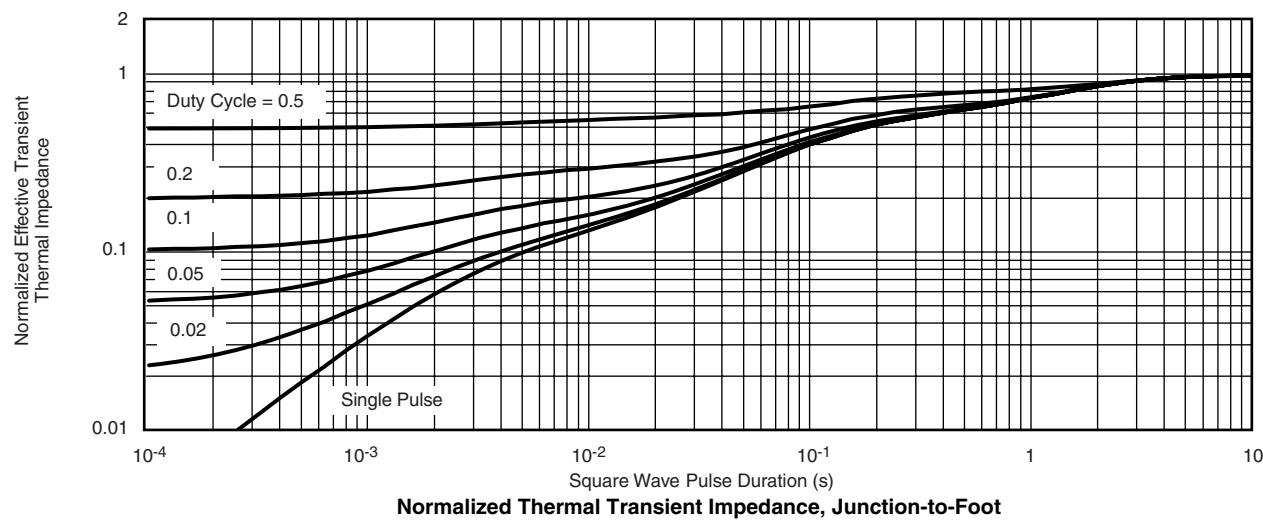
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $25^\circ\text{C}$ , unless otherwise noted



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**On-Resistance vs. Drain Current**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**

**Source-Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted


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